APPLICA	BLE STAN	DARD								
	OPERATING TEMPERATURE RANGE		-35 °C TO +85 °C(NOTE1)		STORAGE TEMPERATURE RANGE		GE	-10 °C TO +60 °C(NO		
RATING	OPERATING		40% TO 80% (NOTE2)		STORAGE	Ē	40% TO 70% (			
	HUMIDITY RANGE		_		HUMIDITY APPLICAE					
	VOLTAGE		250 V AC		CONNEC			DF1E-*S-2. 5C		
	CURRENT		AWG20 TO 24: 3A AWG26: 2A			VOLTAGE		AC 30V		
			AWG28: 1A AWG30: 0.5A		UL, CSA	CURREN	Т	AWG20 TO 22: 3A AWG24 TO 28: 1A AWG30: 0.5A	١	
			SPEC	IFICAT	IONS	)				
רו	EM		TEST METHOD				REQL	JIREMENTS	QT	Α
	RUCTION								1	
	EXAMINATION		Y AND BY MEASURING IN	ISTRUMENT	r. ACC	CORDING	TO DE	RAWING.	X	X
MARKING ELECTRIC CHARA		CONFIRMED VISUALLY.								Х
CONTACT RE			AX, 1 mA(DC OR 1000 F	Hz)	30 n	nΩ MAX.			Х	
MILLIVOLT LE	VEL METHOD.	,				00 11132 W/ VX.				_
INSULATIOI RESISTANO		500 V DC.			100	1000 MΩ MIN.			Х	_
VOLTAGE F		650 V A	C FOR 1 min.		NO	FLASHOV	ER O	R BREAKDOWN.	Х	_
MECHAN	NICAL CHA	RACTE	RISTICS						^	
MECHANIC			INSERTIONS AND EXTRA	CTIONS.	1) (	CONTACT	RESI	STANCE: 30 mΩ MAX.		
OPERATION					(	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Х	_
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			_	<ol> <li>NO ELECTRICAL DISCONTINUITY OF 1 μs.</li> <li>NO DAMAGE, CRACK OR LOOSENESS</li> </ol>			Х	_
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				OF PARTS.				_
ENVIRO	NMENTAL		ACTERISTICS		I				I	1
RAPID CHANGE OF TEMPERATURE					min 2 1	<ol> <li>CONTACT RESISTANCE: 30 mΩ MAX.</li> <li>INSULATION RESISTANCE: 1000 MΩ MIN.</li> <li>NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ol>				_
DAMP HEAT (STEADY STATE)					2 I 3 I	<ol> <li>CONTACT RESISTANCE: 30 mΩ MAX.</li> <li>INSULATION RESISTANCE: 500 MΩ MIN.</li> <li>NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ol>				_
RESISTANCE TO SOLDERING HEAT		1.,			TEF	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			X	_
SOLDERABILITY		SOLDER	FOR INSERTION DURATION, 5 s.			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED			Х	_
NOTE2:NO CO NOTE3:APPL BEFO	UDE THE TEMP ONDENSING. Y TO THE CONE RE PCB ON BOA	ERATURE F DITION OF L ARD. AFTI	RISING BY CURRENT.  ONG TERM STORAGE FOR UER PCB BOARD, OPERATING TO THE PORTION OF T	NUSED PROI TEMPERATUR	DUCTS RE AND	VOI THE	<u> </u>	AGE SEING IMMINIENGED	1	1
COUN	IT DE	SCRIPTIO	ON OF REVISIONS	DI	ESIGNED	)		CHECKED	DA	TE
$\Delta$										
Unless otherwise specified, refer to IE			EC 60512.			APPROVE		KI. AKIYAMA	15. 05. 2	
						CHEC		TS. FUKUSHIMA	15.0	
						DESIG		TS. KUMAZAWA	15. 0 15. 0	
Note QT:Qualification Test AT:Assurance Test X:Applicable Tes					DRAM	/ING NO.	DRAWN MI. SAKIMURA  IG NO. ELC-161951-35			
					ART NO			DF1E-*P-2. 5DS (35)		
11/2			ECTRIC CO., LTD.		ODE NO	,	CL541 2		Δ	1/1
	I IIIOSE EL		-LOTRIO GO., LTD.		ODE INC	<b>/</b> .	OLUTI Z		<u>~~</u>	1/ 1

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